

Bongtae Han

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

176
papers

3,038
citations

27
h-index

50
g-index

216
ext. papers

3,652
ext. citations

2.1
avg, IF

5.41
L-index

#	Paper	IF	Citations
176	Advanced iterative algorithm for phase extraction of randomly phase-shifted interferograms. <i>Optics Letters</i> , 2004 , 29, 1671-3	3	362
175	High Sensitivity Moiré <i>Mechanical Engineering Series</i> , 1994 ,	0.3	325
174	Physics-of-Failure, Condition Monitoring, and Prognostics of Insulated Gate Bipolar Transistor Modules: A Review. <i>IEEE Transactions on Power Electronics</i> , 2015 , 30, 2413-2426	7.2	242
173	Thermal Deformation Analysis of Various Electronic Packaging Products by Moiré and Microscopic Moiré Interferometry. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 1995 , 117, 185-191	2	90
172	Characterization of hygroscopic swelling behavior of mold compounds and plastic packages. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2004 , 27, 499-506		84
171	Moiré Interferometry for engineering mechanics: Current practices and future developments. <i>Journal of Strain Analysis for Engineering Design</i> , 2001 , 36, 101-117	1.3	67
170	Autocorrelation-based time synchronous averaging for condition monitoring of planetary gearboxes in wind turbines. <i>Mechanical Systems and Signal Processing</i> , 2016 , 70-71, 161-175	7.8	62
169	Recent Advancements of Moiré and Microscopic Moiré Interferometry for Thermal Deformation Analyses of Microelectronics Devices. <i>Experimental Mechanics</i> , 1998 , 38, 278-288	2.6	60
168	Study of Residual Stress Distribution by a Combined Method of Moiré Interferometry and Incremental Hole Drilling, Part I: Theory. <i>Journal of Applied Mechanics, Transactions ASME</i> , 1998 , 65, 837-843	2.7	55
167	Higher sensitivity moiré interferometry for micromechanics studies. <i>Optical Engineering</i> , 1992 , 31, 1517	1.1	51
166	Immersion interferometer for microscopic moiré interferometry. <i>Experimental Mechanics</i> , 1992 , 32, 38-41	2.6	50
165	Recent advancements of moiré and microscopic moiré interferometry for thermal deformation analyses of microelectronics devices. <i>Experimental Mechanics</i> , 1998 , 38, 278-288	2.6	47
164	Advanced iterative algorithm for randomly phase-shifted interferograms with intra- and inter-frame intensity variations. <i>Optics and Lasers in Engineering</i> , 2007 , 45, 274-280	4.6	47
163	On Moisture Diffusion Modeling Using Thermal-Moisture Analogy. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2007 , 129, 421-426	2	46
162	THERMAL STRESSES IN MICROELECTRONICS SUBASSEMBLIES: QUANTITATIVE CHARACTERIZATION USING PHOTOMECHANICS METHODS. <i>Journal of Thermal Stresses</i> , 2003 , 26, 583-613	2.2	43
161	Verification of Numerical Models Used in Microelectronics Packaging Design by Interferometric Displacement Measurement Methods. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 1996 , 118, 157-163	2	40
160	Direct Submount Cooling of High-Power LEDs. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2010 , 33, 698-712		39

159	OBSERVING REAL-TIME THERMAL DEFORMATIONS IN ELECTRONIC PACKAGING. <i>Experimental Techniques</i> , 2002 , 26, 25-29	1.4	39
158	Advanced Thermal-Moisture Analogy Scheme for Anisothermal Moisture Diffusion Problem. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2008 , 130,	2	38
157	Recent Applications of Moiré Interferometry. <i>Experimental Mechanics</i> , 2010 , 50, 1129-1147	2.6	37
156	Study of Residual Stress Distribution by a Combined Method of Moiré Interferometry and Incremental Hole Drilling, Part II: Implementation. <i>Journal of Applied Mechanics, Transactions ASME</i> , 1998 , 65, 844-850	2.7	37
155	Determination of an effective coefficient of thermal expansion of electronic packaging components: a whole-field approach. <i>IEEE Transactions on Components and Packaging Technologies</i> , 1996 , 19, 240-247		37
154	Thermal Stresses in a Bimaterial Joint: An Experimental Analysis. <i>Journal of Applied Mechanics, Transactions ASME</i> , 1994 , 61, 192-198	2.7	30
153	Development of real time/variable sensitivity warpage measurement technique and its application to plastic ball grid array package. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 1999 , 22, 63-70		29
152	Interferometric methods with enhanced sensitivity by optical/digital fringe multiplication. <i>Applied Optics</i> , 1993 , 32, 4713-8	1.7	28
151	A localized hybrid method of stress analysis: A combination of moiré interferometry and FEM. <i>Experimental Mechanics</i> , 1990 , 30, 195-200	2.6	28
150	Hierarchical Life Prediction Model for Actively Cooled LED-Based Luminaire. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2010 , 33, 728-737		27
149	Deformation Mechanism of Two-Phase Solder Column Interconnections Under Highly Accelerated Thermal Cycling Condition: An Experimental Study. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 1997 , 119, 189-196	2	26
148	On the design parameters of flip-chip PBGA package assembly for optimum solder ball reliability. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2001 , 24, 300-307		24
147	Simultaneous Measurement of Effective Chemical Shrinkage and Modulus Evolutions During Polymerization. <i>Experimental Mechanics</i> , 2011 , 51, 1155-1169	2.6	22
146	MEASUREMENT OF THE HYGROSCOPIC SWELLING COEFFICIENT IN MOLD COMPOUNDS USING MOIRÉ INTERFEROMETRY. <i>Experimental Techniques</i> , 2003 , 27, 40-44	1.4	22
145	Micro-Mechanical Deformation Analysis of Surface Laminae Circuit in Organic Flip-Chip Package: An Experimental Study. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2000 , 122, 294-300	2	22
144	Warpage Measurement on Dielectric Rough Surfaces of Microelectronics Devices by Far Infrared Fizeau Interferometry1. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2000 , 122, 227-232	2	22
143	Analytical/Experimental Hybrid Approach Based on Spectral Power Distribution for Quantitative Degradation Analysis of Phosphor Converted LED. <i>IEEE Transactions on Device and Materials Reliability</i> , 2014 , 14, 365-374	1.6	21
142	. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2010 , 33, 809-818		21

141	Temperature Dependent Deformation Analysis of Ceramic Ball Grid Array Package Assembly Under Accelerated Thermal Cycling Condition. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2004 , 126, 41-47	2	21
140	Thick Composites in Compression: An Experimental Study of Micromechanical Behavior and Smeared Engineering Properties. <i>Journal of Composite Materials</i> , 1992 , 26, 1930-1944	2.7	21
139	Moiré Methods for Engineering and Science [Moiré Interferometry and Shadow Moiré] 2000 , 151-196		21
138	Optimum design domain of LED-based solid state lighting considering cost, energy consumption and reliability. <i>Microelectronics Reliability</i> , 2013 , 53, 435-442	1.2	20
137	On Ultra-Fine Leak Detection of Hermetic Wafer Level Packages. <i>IEEE Transactions on Advanced Packaging</i> , 2008 , 31, 14-21		20
136	Error analysis of the phase-shifting technique when applied to shadow moiré <i>Applied Optics</i> , 2006 , 45, 1124-33	1.7	20
135	Inverse method to determine elastic constants using a circular disk and moiré Interferometry. <i>Experimental Mechanics</i> , 2005 , 45, 27-34	2.6	20
134	Algorithm to Determine the Knee Point on Capacity Fade Curves of Lithium-Ion Cells. <i>Energies</i> , 2019 , 12, 2910	3.1	19
133	Measurement of the Hygroscopic Swelling Coefficient of Thin Film Polymers Used in Semiconductor Packaging. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2010 , 33, 340-346		18
132	Nonlinear Stress Modeling Scheme to Analyze Semiconductor Packages Subjected to Combined Thermal and Hygroscopic Loading. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2008 , 130,	2	18
131	Integrated Measurement Technique for Curing Process-Dependent Mechanical Properties of Polymeric Materials Using Fiber Bragg Grating. <i>Experimental Mechanics</i> , 2008 , 48, 107-117	2.6	18
130	Inverse Method to Determine Elastic Constants Using a Circular Disk and Moire Interferometry. <i>Experimental Mechanics</i> , 2005 , 45, 27-34	2.6	18
129	Spectral power distribution deconvolution scheme for phosphor-converted white light-emitting diode using multiple Gaussian functions. <i>Applied Optics</i> , 2013 , 52, 1016-24	1.7	17
128	Effect of junction temperature on heat dissipation of high power light emitting diodes. <i>Journal of Applied Physics</i> , 2016 , 119, 125104	2.5	16
127	Life prediction of LED-based recess downlight cooled by synthetic jet. <i>Microelectronics Reliability</i> , 2012 , 52, 937-948	1.2	15
126	A strain range based model for life assessment of Pb-free SAC solder interconnects		15
125	Characterization of flexural and thermo-mechanical behavior of plastic ball grid package assembly using moiré Interferometry. <i>Microelectronics Reliability</i> , 2005 , 45, 637-646	1.2	14
124	Far-infrared fizeau interferometry. <i>Applied Optics</i> , 2001 , 40, 4981-7	1.7	14

123	Board level reliability analysis of chip resistor assemblies under thermal cycling: A comparison study between SnPb and SnAgCu. <i>Journal of Mechanical Science and Technology</i> , 2014 , 28, 879-886	1.6	13
122	Moiré Interferometry. <i>Mechanical Engineering Series</i> , 1994 , 135-226	0.3	13
121	Coupled Thermal and Thermo-Mechanical Design Assessment of High Power Light Emitting Diode. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2010 , 33, 688-697		12
120	Moiré Interferometry. <i>Springer Handbooks</i> , 2008 , 627-654	1.3	12
119	Measurement of effective chemical shrinkage and equilibrium modulus of silicone elastomer used in potted electronic system. <i>Journal of Materials Science</i> , 2014 , 49, 8301-8310	4.3	11
118	Numerical study on the mixing performance of a ring-type electroosmotic micromixer with different obstacle configurations. <i>Journal of Nanoscience and Nanotechnology</i> , 2012 , 12, 4523-30	1.3	11
117	High Sensitivity Shadow Moiré Using Nonzero-Order Talbot Distance. <i>Experimental Mechanics</i> , 2006 , 46, 543-554	2.6	11
116	Contrast of shadow moiré at high-order Talbot distances. <i>Optical Engineering</i> , 2005 , 44, 028002	1.1	11
115	Method for predicting junction temperature distribution in a high-power laser diode bar. <i>Applied Optics</i> , 2016 , 55, 7487-96	0.2	11
114	Moisture Ingress, Behavior, and Prediction Inside Semiconductor Packaging: A Review. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2017 , 139,	2	10
113	Generalized Hybrid Modeling to Determine Chemical Shrinkage and Modulus Evolutions at Arbitrary Temperatures. <i>Experimental Mechanics</i> , 2013 , 53, 1783-1790	2.6	10
112	A compact, robust and versatile moiré interferometer. <i>Optics and Lasers in Engineering</i> , 1995 , 23, 29-40	4.6	10
111	Numerical/Experimental Hybrid Approach to Predict Warpage of Thin Advanced Substrates 2018 ,		9
110	Dual-Configuration Fiber Bragg Grating Sensor Technique to Measure Coefficients of Thermal Expansion and Hygroscopic Swelling. <i>Experimental Mechanics</i> , 2014 , 54, 593-603	2.6	9
109	Measurements of true leak rates of MEMS packages. <i>Sensors</i> , 2012 , 12, 3082-104	3.8	9
108	Hermeticity Evaluation of Polymer-Sealed MEMS Packages by Gas Diffusion Analysis. <i>Journal of Microelectromechanical Systems</i> , 2009 , 18, 577-587	2.5	9
107	Ideal laminate theory for water transport analysis of metal-coated polymer films. <i>Applied Physics Letters</i> , 2008 , 93, 133307	3.4	9
106	MEASUREMENT OF THERMAL EXPANSION COEFFICIENT OF FLEXIBLE SUBSTRATE BY MOIRÉ INTERFEROMETRY. <i>Experimental Techniques</i> , 2001 , 25, 22-25	1.4	9

105	Towards prognostics and health monitoring: The potential of fault detection by piezoresistive silicon stress sensor 2016 ,		9
104	Advanced Mechanical/Optical Configuration of Real-Time Moiré Interferometry for Thermal Deformation Analysis of Fan-Out Wafer Level Package. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2018 , 8, 764-772	1.7	8
103	In-situ investigation of EMC relaxation behavior using piezoresistive stress sensor. <i>Microelectronics Reliability</i> , 2016 , 62, 58-62	1.2	8
102	Adhesion and Puncture Strength of Polyurethane Coating Used to Mitigate Tin Whisker Growth. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2014 , 136,	2	8
101	Thermo-optical modeling of polymer fiber Bragg grating illuminated by light emitting diode. <i>International Journal of Heat and Mass Transfer</i> , 2007 , 50, 5241-5248	4.9	8
100	Micromechanical deformation analysis of beta alloy titanium in elastic and elastic/plastic tension. <i>Experimental Mechanics</i> , 1996 , 36, 120-126	2.6	8
99	Geometric moiré methods with enhanced sensitivity by optical/digital fringe multiplication. <i>Experimental Mechanics</i> , 1993 , 33, 195-200	2.6	8
98	Measurement of Elastic Properties of Epoxy Molding Compound by Single Cylindrical Configuration with Embedded Fiber Bragg Grating Sensor. <i>Experimental Mechanics</i> , 2017 , 57, 313-324	2.6	7
97	Prognostic approaches for the wirebond failure prediction in power semiconductors: A case study using DPAK package 2015 ,		7
96	Development of a High-Lumen Solid State Down Light Application. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2010 , 33, 668-679		7
95	Analytical solutions of gas transport problems in inorganic/organic hybrid structures for gas barrier applications. <i>Journal of Applied Physics</i> , 2009 , 105, 093532	2.5	7
94	THE TILTED-PLATE METHOD FOR INTRODUCING CARRIER FRINGES OF EXTENSION IN MOIRÉ INTERFEROMETRY. <i>Experimental Techniques</i> , 2008 , 13, 25-29	1.4	7
93	On the applicability of MIL-Spec-based helium fine leak test to packages with sub-micro liter cavity volumes. <i>Microelectronics Reliability</i> , 2008 , 48, 1815-1821	1.2	7
92	Measurement of anisotropic coefficients of thermal expansion of SAC305 solder using surface strains of single grain with arbitrary orientation. <i>Acta Materialia</i> , 2018 , 156, 196-204	8.4	7
91	Assembly yield prediction of plastically encapsulated packages with a large number of manufacturing variables by advanced approximate integration method. <i>Microelectronics Reliability</i> , 2017 , 78, 319-330	1.2	6
90	. <i>IEEE Sensors Journal</i> , 2019 , 19, 9139-9148	4	6
89	\$In Situ\$ Failure Detection of Electronic Control Units Using Piezoresistive Stress Sensor. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2018 , 8, 750-763	1.7	6
88	Phase-shifting in achromatic moiré interferometry system. <i>Optics Express</i> , 2007 , 15, 9970-6	3.3	6

87	Thermo-optical modeling of an intrinsically heated polymer fiber Bragg grating. <i>Applied Optics</i> , 2007 , 46, 4357-70	1.7	6
86	Real-time observation of thermally induced warpage of flip-chip package using far-infrared Fizeau interferometry. <i>Experimental Mechanics</i> , 2004 , 44, 628-633	2.6	6
85	In-situ investigation of EMC relaxation behavior using piezoresistive stress sensor 2015 ,		5
84	Probabilistic Lifetime Prediction of Electronic Packages Using Advanced Uncertainty Propagation Analysis and Model Calibration. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2016 , 6, 238-248	1.7	5
83	Towards prognostics and health monitoring: The potential of fault detection by piezoresistive silicon stress sensor. <i>Microelectronics Reliability</i> , 2017 , 74, 165-172	1.2	5
82	Deconvolution of spectral power distribution of high-power laser diode arrays. <i>Applied Optics</i> , 2017 , 56, 5590-5598	1.7	5
81	Analytical and molecular simulation study of water condensation behavior in mesopores with closed ends. <i>Journal of Chemical Physics</i> , 2010 , 132, 104702	3.9	5
80	Real-time warpage measurement of electronic components with variable sensitivity		5
79	Measurement of Hygroscopic Swelling in Mold Compounds and Its Effect on PEM Reliability 2003 , 497		5
78	Degradation Estimation and Prediction of Electronic Packages using Data Driven Approach. <i>IEEE Transactions on Industrial Electronics</i> , 2021 , 1-1	8.9	5
77	Volumetric effective cure shrinkage measurement of dual curable adhesives by fiber Bragg grating sensor. <i>Journal of Materials Science</i> , 2020 , 55, 9655-9664	4.3	4
76	Hybrid Approach to Conduct Failure Prognostics of Automotive Electronic Control Unit Using Stress Sensor as In Situ Load Counter. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019 , 9, 28-38	1.7	4
75	. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2015 , 5, 1635-1643	1.7	4
74	In situ measurement of gas diffusion properties of polymeric seals used in MEMS packages by optical gas leak testing. <i>Journal of Micro/Nanolithography, MEMS, and MOEMS</i> , 2009 , 8, 043025	0.7	4
73	Sensitivity enhancement of far-infrared Fizeau interferometry by digital image processing. <i>Optical Engineering</i> , 2001 , 40, 1970	1.1	4
72	Condition Monitoring Algorithm for Piezoresistive Silicon-Based Stress Sensor Data Obtained from Electronic Control Units 2017 ,		3
71	Prediction of Statistical Distribution of Vibration-Induced Solder Fatigue Failure Considering Intrinsic Variations of Mechanical Properties of Anisotropic Sn-Rich Solder Alloys 2018 ,		3
70	Characterization of Linear Viscoelastic Behavior of Epoxy Molding Compound Subjected to Uniaxial Compression and Hydrostatic Pressure. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2018 , 8, 1363-1372	1.7	3

69	Degradation analysis of secondary lens system and its effect on performance of LED-based luminaire. <i>Microelectronics Reliability</i> , 2014 , 54, 131-137	1.2	3
68	Quantitative Characterization of True Leak Rate of Micro to Nanoliter Packages Using Helium Mass Spectrometer. <i>IEEE Transactions on Advanced Packaging</i> , 2009 , 32, 440-447		3
67	Nano-Pattern Recognition and Correlation Technique for Sub-Nanometer In-Plane Displacement Measurement. <i>Experimental Mechanics</i> , 2010 , 50, 1169-1181	2.6	3
66	Geometric Moiré <i>Springer Handbooks</i> , 2008 , 601-626	1.3	3
65	Fiber Bragg Grating Sensor to Characterize Curing Process-dependent Mechanical Properties of Polymeric Materials 2007 ,		3
64	Non-linear finite element analysis for electronic packages subjected to combined hygroscopic and thermo-mechanical stresses		3
63	Stacking Yield Prediction of Package-on-Package Assembly Using Advanced Uncertainty Propagation Analysis: Part I Stochastic Model Development. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2020 , 142,	2	3
62	Stacking Yield Prediction of Package-on-Package Assembly Using Uncertainty Propagation Analysis Part II: Implementation of Stochastic Model. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2020 , 142,	2	3
61	Moiré Interferometry 2000 , 375-389		3
60	Test Scheme and Degradation Model of Accumulated Electrostatic Discharge (ESD) Damage for Insulated Gate Bipolar Transistor (IGBT) Prognostics. <i>IEEE Transactions on Device and Materials Reliability</i> , 2019 , 19, 233-241	1.6	3
59	Study of Thermal Aging Behavior of Epoxy Molding Compound for Applications in Harsh Environments 2019 ,		3
58	Characterization of Stresses and Strains in Microelectronics and Photonics Devices Using Photomechanics Methods 2007 , A475-A522		3
57	Degradation Prediction of Electronic Packages using Machine Learning 2019 ,		2
56	In-situ service load monitoring of automotive electronic systems using silicon-based piezoresistive stress sensor. <i>Microelectronics Reliability</i> , 2020 , 110, 113650	1.2	2
55	Thermal Characterization of Die-Attach Material Interface of High-Power Light-Emitting Diodes. <i>Solid State Lighting Technology and Application Series</i> , 2018 , 159-178	0.7	2
54	Modified single cantilever adhesion test for EMC/PSR interface in thin semiconductor packages. <i>Microelectronics Reliability</i> , 2016 , 63, 134-141	1.2	2
53	Hygrothermal Behavior of Advanced Polymers Above Water Boiling Temperatures. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2014 , 136,	2	2
52	Hybrid Approach to Conduct Failure Prognostics of Automotive Electronic Control Unit 2017 ,		2

51	Prognostics and health monitoring of electronic system: A review 2017 ,		2
50	Non-linear Viscoelastic Modeling of Epoxy Based Molding Compound for Large Deformations Encountered in Power Modules 2017 ,		2
49	Modeling of Moisture Diffusion and Moisture-Induced Stresses in Semiconductor and MEMS Packages 2010 , 181-219		2
48	Forward-stepwise regression analysis for fine leak batch testing of wafer-level hermetic MEMS packages. <i>Microelectronics Reliability</i> , 2010 , 50, 507-513	1.2	2
47	Thermofluid characteristics of two-phase flow in micro-gap channels. <i>Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems</i> , 2008 ,		2
46	Thermofluid Characteristics of Two-Phase Microgap Coolers 2007 ,		2
45			2
44	Micromechanical thermal deformation analysis of unidirectional boron/aluminum metal-matrix composite. <i>Optics and Lasers in Engineering</i> , 1996 , 24, 455-466	4.6	2
43	ISOCHROMATIC FRINGE SHARPENING AND MULTIPLICATION. <i>Experimental Techniques</i> , 1994 , 18, 11-13	1.4	2
42	High temperature aging of epoxy-based molding compound and its effect on mechanical behavior of molded electronic package. <i>Polymer Degradation and Stability</i> , 2021 , 188, 109572	4.7	2
41	Towards virtual twin for electronic packages in automotive applications. <i>Microelectronics Reliability</i> , 2021 , 122, 114134	1.2	2
40	Measurement of effective cure shrinkage of epoxy-based molding compound by fiber Bragg grating sensor using two-stage curing process. <i>Journal of Applied Polymer Science</i> , 51620	2.9	2
39	Microscopic Moiré Interferometry: Very High Sensitivity. <i>Mechanical Engineering Series</i> , 1994 , 227-255	0.3	2
38	Thermal deformation analysis of automotive electronic control units subjected to passive and active thermal conditions 2015 ,		1
37	Moisture Transport Through Housing Materials Enclosing Critical Automotive Electronics. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 541-550	1.7	1
36	Stacking Yield Prediction of Package-on-Package Considering the Statistical Distributions of Top/Bottom Package Warpages and Solder Ball Heights 2018 ,		1
35	Effects of Underfill on Thermo-Mechanical Behavior of Fan-out Wafer Level Package Used in PoP: An Experimental Study by Advancements of Real-Time Moiré Interferometry 2018 ,		1
34	Advanced Co-Planarity Measurement Tools for the Warpage Investigation of Non-Conventional Packages Caused by Reflow and Assembly Process 2007 ,		1

33			1
32	Whole-field Displacement Measurement Techniques for Thermal Deformation Analyses of Electronic Packages. <i>Materials Research Society Symposia Proceedings</i> , 1998 , 515, 167		1
31	MECHANICAL FRINGE SHIFTING IN MOIRE INTERFEROMETRY. <i>Experimental Techniques</i> , 1999 , 23, 16-19	1.4	1
30	Bottom leaded plastic (BLP) package: a new design with enhanced solder joint reliability		1
29	Prediction of Statistical Distribution of Solder Joint Fatigue Lifetime Using Hybrid Probabilistic Approach. <i>Conference Proceedings of the Society for Experimental Mechanics</i> , 2015 , 165-169	0.3	1
28	Thermal Stresses Near the Interface of a Bimaterial Joint. <i>Mechanical Engineering Series</i> , 1994 , 293-312	0.3	1
27	Blister Testing for Adhesion Strength Measurement of Polymer Films Subjected to Environmental Conditions. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2016 , 138,	2	1
26	Thermal and optical performance of cryogenically cooled laser diode bars mounted on pin-finned microcoolers. <i>Applied Physics B: Lasers and Optics</i> , 2021 , 127, 1	1.9	1
25			
24	EMC Oxidation Under High-Temperature Aging 2022 , 53-80		0
23	Effect of critical properties of epoxy molding compound on warpage prediction: A critical review. <i>Microelectronics Reliability</i> , 2022 , 130, 114480	1.2	0
22	Thermal Performance of Cryogenic Micro-Pin Fin Coolers with Two-Phase Liquid Nitrogen Flows. <i>Applied Sciences (Switzerland)</i> , 2021 , 11, 11071	2.6	0
21	Measurements of Inelastic Strain Evolution of Single Solder Grain Subject to Nominal Shear Loading. <i>Experimental Mechanics</i> , 2019 , 59, 1075-1086	2.6	
20	Advanced Statistical Model Calibration to Determine Manufacturing-Induced Variations of Effective Elastic Properties of SAC Solder Joints in Leadless Chip Resistor Assemblies. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019 , 9, 797-804	1.7	
19	Hierarchical Reliability Assessment Models for Novel LED-Based Recessed Down Lighting Systems 2013 , 455-495		
18	Modified coupled-mode model for thermally chirped polymer Bragg gratings. <i>Applied Optics</i> , 2010 , 49, 2079-84	0.2	
17	Thermal-structural modeling of polymer Bragg grating waveguides illuminated by a light emitting diode. <i>Applied Optics</i> , 2012 , 51, 726-34	1.7	
16	An Advanced Real-Time Moire Interferometry System With Conductive Heating/Cooling and Its Application on a Creep Behavior of Solder 2007 , 479		

- 15 Infrared diffraction interferometer for coplanarity measurement of high-density solder bump pattern. *Optical Engineering*, **2004**, 43, 888 1.1
- 14 Isochromatic fringe sharpening and interpolation along an isoclinic contour, with application to fracture mechanics. *Experimental Mechanics*, **1996**, 36, 305-311 2.6
- 13 Strain Measurements At The Limit - The Moiré Microscope. *Series in Optics and Optoelectronics*, **2003**, 3-48
- 12 Electronic Packaging. *Series in Optics and Optoelectronics*, **2003**, 121-175
- 11 Out-Of-Plane Deformation, Flatness And Shape Measurement. *Series in Optics and Optoelectronics*, **2003**, 373-424
- 10 OS1-2-1 In-situ Nano-scale Thermal Deformation Measurements Using Nano-Pattern Recognition and Correlation Technique. *The Abstracts of ATEM International Conference on Advanced Technology in Experimental Mechanics Asian Conference on Experimental Mechanics*, **2007**, 2007.6, _OS1-2-1-1-_OS1-2-1-6 0.3
- 9 Recent Developments and Applications of Photomechanics Methods for Microelectronics Product Development **2007**, 15-16
- 8 Nonlinear Compressible Finite Viscoelasticity of Epoxy-Based Polymers **2019**, 335-340
- 7 Textile Composites. *Mechanical Engineering Series*, **1994**, 313-329 0.3
- 6 Laminated Composites in Compression: Free-edge Effects. *Mechanical Engineering Series*, **1994**, 273-292 0.3
- 5 Comprehensive Viscoelastic Properties Characterization of EMC Using FBG Sensor. *Conference Proceedings of the Society for Experimental Mechanics*, **2017**, 173-180 0.3
- 4 Characterization of Hygroscopic Deformations by Moiré Interferometry **2010**, 113-130
- 3 Reliability Evaluation of Conformal Coatings for Tin Whisker Failure Mitigation in Accelerated Testing Conditions. *Conference Proceedings of the Society for Experimental Mechanics*, **2011**, 107-108 0.3
- 2 Rapid Characterization of Visco-elastic Properties of Polymeric Materials. *Conference Proceedings of the Society for Experimental Mechanics*, **2011**, 287-288 0.3
- 1 Hierarchical Reliability Model for Life Prediction of Actively Cooled LED-Based Luminaire. *Conference Proceedings of the Society for Experimental Mechanics*, **2011**, 189-190 0.3